Renesas Electronics America Inc - UPD78F0532AGK-GAJ-AX Datasheet

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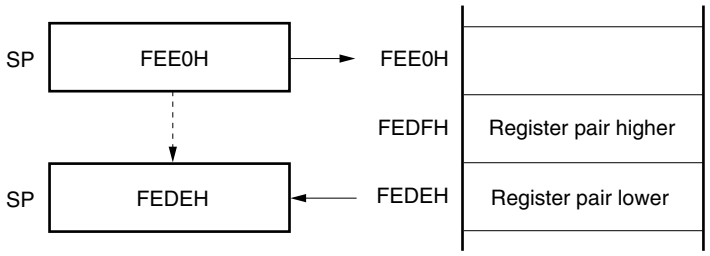
Applications of "Embedded - Microcontrollers"

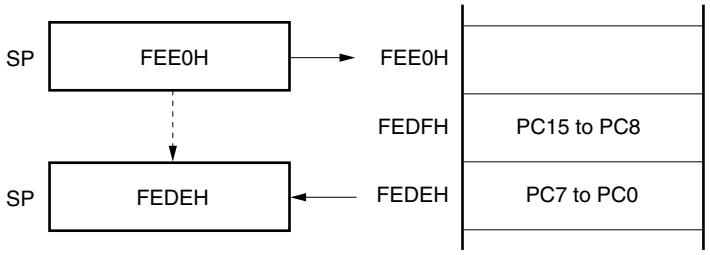
Details	
Product Status	Active
Core Processor	78K/0
Core Size	8-Bit
Speed	20MHz
Connectivity	3-Wire SIO, I²C, LINbus, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	55
Program Memory Size	24KB (24K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/upd78f0532agk-gaj-ax

Figure 3-23. Data to Be Saved to Stack Memory

(a) PUSH rp instruction (when SP = FEE0H)



(b) CALL, CALLF, CALLT instructions (when SP = FEE0H)



(c) Interrupt, BRK instructions (when SP = FEE0H)

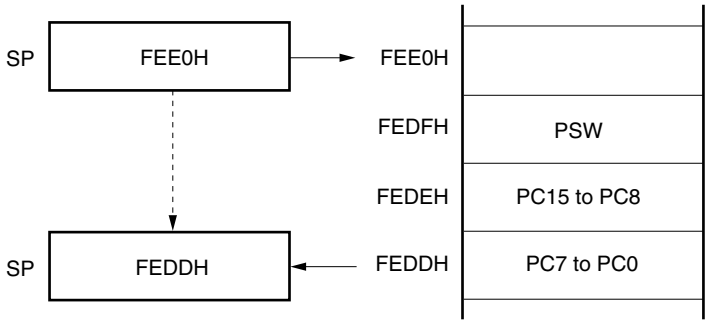
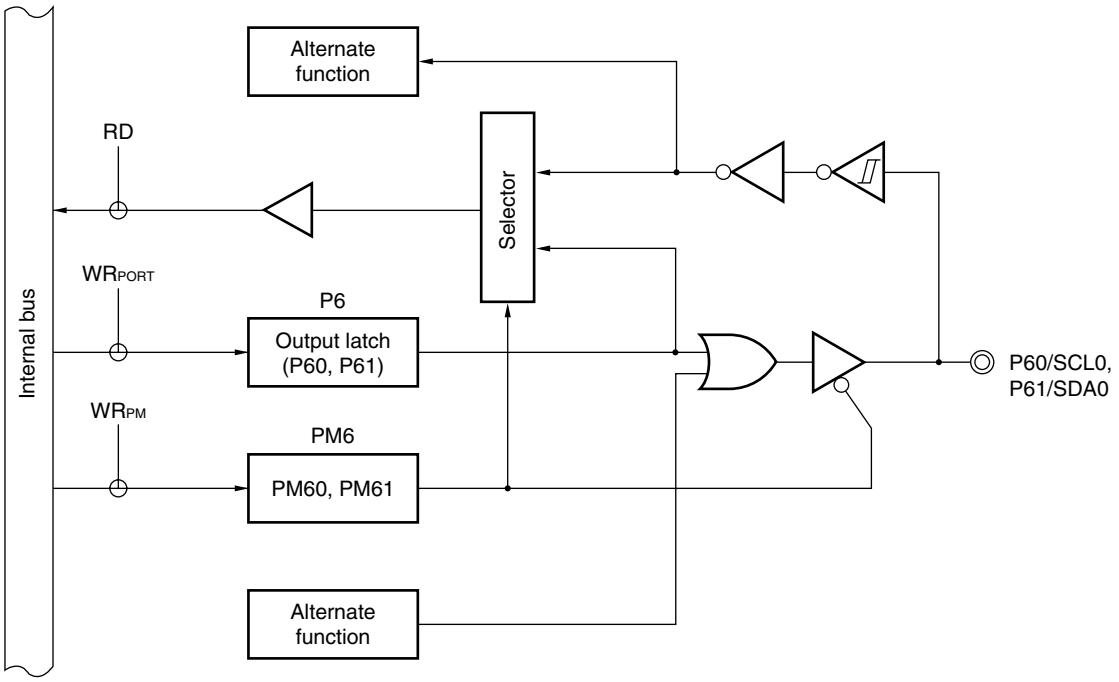


Figure 5-17. Block Diagram of P60 and P61



P6: Port register 6
PM6: Port mode register 6
RD: Read signal
WR××: Write signal

Caution A through current flows through P60 and P61 if an intermediate potential is input to these pins, because the input buffer is also turned on when P60 and P61 are in output mode. Consequently, do not input an intermediate potential when P60 and P61 are in output mode.

(3) Example of setting procedure when using the subsystem clock as the CPU clock

<1> Setting subsystem clock oscillation[Note]

(See **6.6.3 (1) Example of setting procedure when oscillating the XT1 clock** and **(2) Example of setting procedure when using the external subsystem clock**.)

Note The setting of <1> is not necessary when while the subsystem clock is operating.

<2> Switching the CPU clock (PCC register)

When CSS is set to 1, the subsystem clock is supplied to the CPU.

CSS	PCC2	PCC1	PCC0	CPU Clock (f_{CPU}) Selection
1	0	0	0	f_{SUB}/2
	0	0	1	
	0	1	0	
	0	1	1	
	1	0	0	
	Other than above			Setting prohibited

(4) Example of setting procedure when stopping the subsystem clock

<1> Confirming the CPU clock status (PCC and MCM registers)

Confirm with CLS and MCS that the CPU is operating on a clock other than the subsystem clock.

When CLS = 1, the subsystem clock is supplied to the CPU, so change the CPU clock to a clock other than the subsystem clock.

CLS	MCS	CPU Clock Status
0	0	Internal high-speed oscillation clock
0	1	High-speed system clock
1	×	Subsystem clock

<2> Stopping the subsystem clock (OSCCTL register)

When OSCSELS is cleared to 0, XT1 oscillation is stopped (the input of the external clock is disabled).

Cautions 1. Be sure to confirm that CLS = 0 when clearing OSCSELS to 0. In addition, stop the watch timer if it is operating on the subsystem clock.

2. The subsystem clock oscillation cannot be stopped using the STOP instruction.

7.2 Configuration of 16-Bit Timer/Event Counters 00 and 01

16-bit timer/event counters 00 and 01 include the following hardware.

Table 7-1. Configuration of 16-Bit Timer/Event Counters 00 and 01

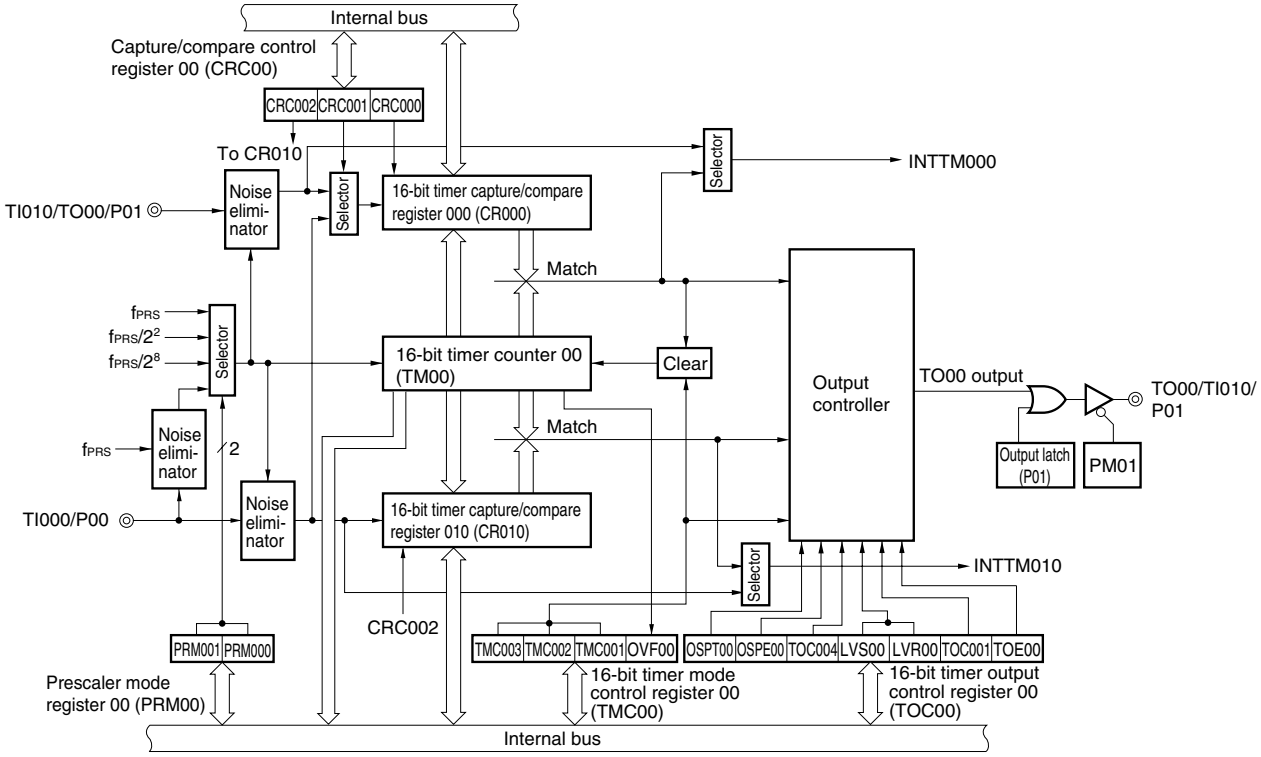
Item	Configuration
Time/counter	16-bit timer counter 0n (TM0n)
Register	16-bit timer capture/compare registers 00n, 01n (CR00n, CR01n)
Timer input	TI00n, TI01n pins
Timer output	TO0n pin, output controller
Control registers	16-bit timer mode control register 0n (TMC0n) 16-bit timer capture/compare control register 0n (CRC0n) 16-bit timer output control register 0n (TOC0n) Prescaler mode register 0n (PRM0n) Port mode register 0 (PM0) Port register 0 (P0)

Remark n = 0: 78K0/KE2 products whose flash memory is less than 32 KB, and 78K0/KB2, 78K0/KC2, 78K0/KD2 products

n = 0, 1: 78K0/KE2 products whose flash memory is at least 48 KB, and 78K0/KF2 products

Figures 7-1 and 7-2 show the block diagrams.

Figure 7-1. Block Diagram of 16-Bit Timer/Event Counter 00



(Cautions 1 to 3 are listed on the next page.)

8.4.3 Square-wave output operation

A square wave with any selected frequency is output at intervals determined by the value preset to 8-bit timer compare register 5n (CR5n).

The TO5n pin output status is inverted at intervals determined by the count value preset to CR5n by setting bit 0 (TOE5n) of 8-bit timer mode control register 5n (TMC5n) to 1. This enables a square wave with any selected frequency to be output (duty = 50%).

Setting

<1> Set each register.

- Clear the port output latch (P17 or P33)[Note] and port mode register (PM17 or PM33)[Note] to 0.
- TCL5n: Select the count clock.
- CR5n: Compare value
- TMC5n: Stop the count operation, select the mode in which clear & start occurs on a match of TM5n and CR5n.

LVS5n	LVR5n	Timer Output F/F Status Setting
0	1	Timer output F/F clear (0) (default value of TO5n output: low level)
1	0	Timer output F/F set (1) (default value of TO5n output: high level)

Timer output enabled
(TMC5n = 00001011B or 00000111B)

<2> After TCE5n = 1 is set, the count operation starts.

<3> The timer output F/F is inverted by a match of TM5n and CR5n. After INTTM5n is generated, TM5n is cleared to 00H.

<4> After these settings, the timer output F/F is inverted at the same interval and a square wave is output from TO5n. The frequency is as follows.

- Frequency = 1/2t (N + 1)
  (N: 00H to FFH)

Note 8-bit timer/event counter 50: P17, PM17
8-bit timer/event counter 51: P33, PM33

Caution Do not write other values to CR5n during operation.

Remarks 1. For how to enable the INTTM5n signal interrupt, see **CHAPTER 20 INTERRUPT FUNCTIONS**.
2. n = 0, 1

CHAPTER 12 CLOCK OUTPUT/BUZZER OUTPUT CONTROLLER

	78K0/KB2	78K0/KC2	78K0/KD2	78K0/KE2	78K0/KF2
Clock output	–	38/44 pins: – 48 pins: √	√		
Buzzer output	–			√	

Remark √: Mounted, –: Not mounted

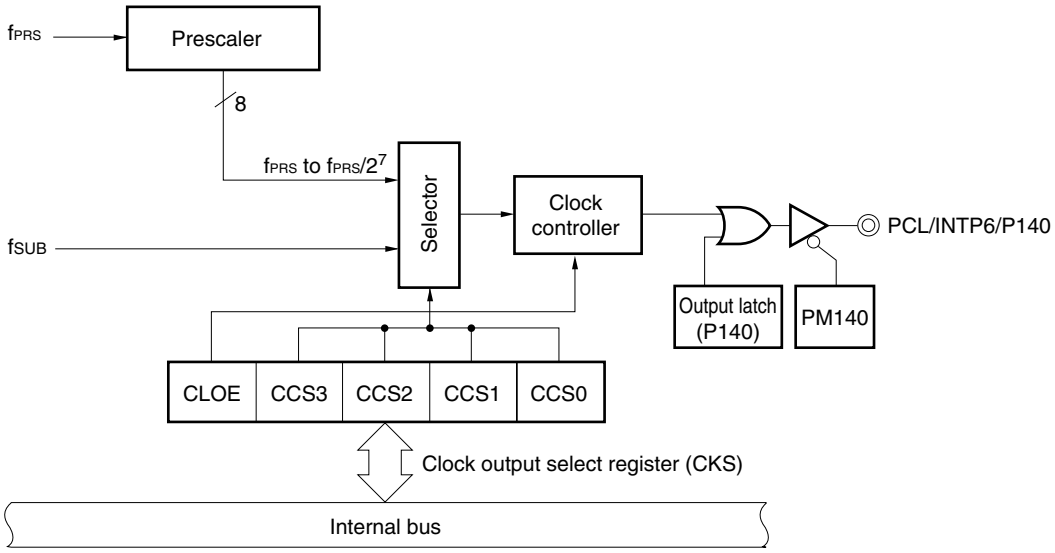
12.1 Functions of Clock Output/Buzzer Output Controller

The clock output controller is intended for carrier output during remote controlled transmission and clock output for supply to peripheral ICs. The clock selected with the clock output selection register (CKS) is output.

In addition, the buzzer output is intended for square-wave output of buzzer frequency selected with CKS.

Figure 12-1 and 12-2 show the block diagram of clock output/buzzer output controller.

Figure 12-1. Block Diagram of Clock Output/Buzzer Output Controller (78K0/KD2, 48-pin Products of 78K0/KC2)



(5) A/D port configuration register (ADPC)

This register switches the ANI0/P20 to ANI7/P27 pins to analog input of A/D converter or digital I/O of port.

ADPC can be set by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation clears this register to 00H.

Remark ANI0 to ANI3: 78K0/KB2
ANI0 to ANI5: 38-pin products of the 78K0/KC2
ANI0 to ANI7: Products other than above

Figure 13-9. Format of A/D Port Configuration Register (ADPC)

Address: FF2FH After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
ADPC	0	0	0	0	ADPC3	ADPC2	ADPC1	ADPC0

Products other than the right: Note 1
38-pin products of KC2: Note 1, Note 2
KB2: Note 1, Note 2

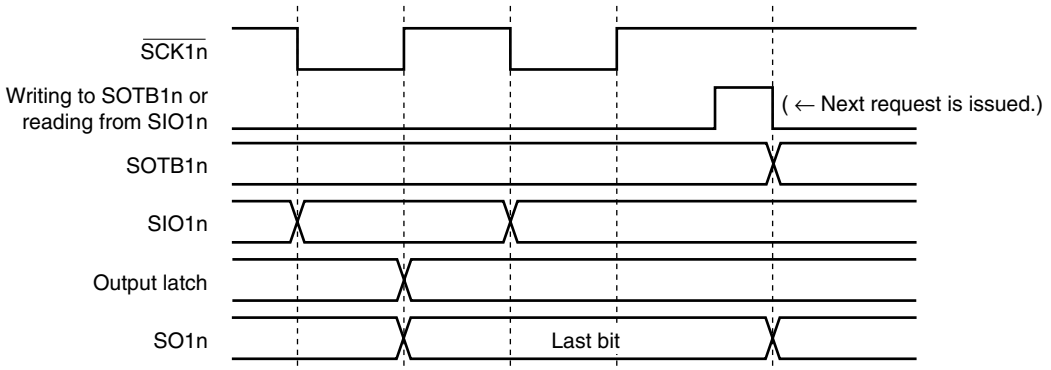
ADPC3	ADPC2	ADPC1	ADPC0	Digital I/O (D)/analog input (A) switching							
				P27/ ANI7	P26/ ANI6	P25/ ANI5	P24/ ANI4	P23/ ANI3	P22/ ANI2	P21/ ANI1	P20/ ANI0
0	0	0	0	A	A	A	A	A	A	A	A
0	0	0	1	A	A	A	A	A	A	A	D
0	0	1	0	A	A	A	A	A	A	D	D
0	0	1	1	A	A	A	A	A	D	D	D
0	1	0	0	A	A	A	A	D	D	D	D
0	1	0	1	A	A	A	D	D	D	D	D
0	1	1	0	A	A	D	D	D	D	D	D
0	1	1	1	A	D	D	D	D	D	D	D
1	0	0	0	D	D	D	D	D	D	D	D
Other than above				Setting prohibited							

Notes 1. Setting permitted
2. Setting prohibited

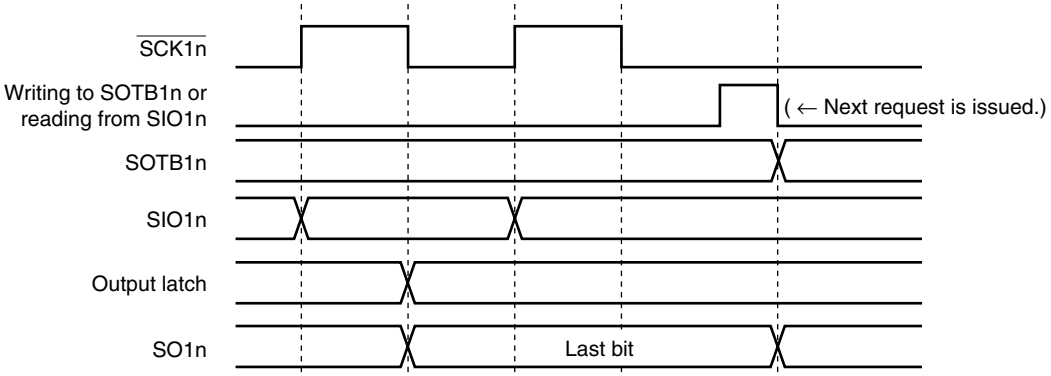
Cautions 1. Set a channel to be used for A/D conversion in the input mode by using port mode register 2 (PM2).
2. If data is written to ADPC, a wait cycle is generated. Do not write data to ADPC when the peripheral hardware clock (f_{PRS}) is stopped. For details, see CHAPTER 36 CAUTIONS FOR WAIT.

Figure 16-12. Output Value of SO1n Pin (Last Bit) (2/2)

(c) Type 2: CKP1n = 0, DAP1n = 1



(d) Type 4: CKP1n = 1, DAP1n = 1



Remark n = 0: 78K0/KE2 products whose flash memory is less than 32 KB, and 78K0/KB2, 78K0/KC2, 78K0/KD2 products

n = 0, 1: 78K0/KE2 products whose flash memory is at least 48 KB, and 78K0/KF2 products

(4) Divisor selection register 0 (BRGCA0)

This is an 8-bit register used to select the base clock divisor of CSIA0.

This register can be set by an 8-bit memory manipulation instruction. However, when bit 0 (TSF0) of serial status register 0 (CSIS0) is 1, rewriting BRGCA0 is prohibited.

Reset signal generation sets this register to 03H.

Figure 17-5. Format of Divisor Selection Register 0 (BRGCA0)

Address: FF93H After reset: 03H R/W

Symbol	7	6	5	4	3	2	1	0
BRGCA0	0	0	0	0	0	0	BRGCA01	BRGCA00

BRGCA01	BRGCA00	Selection of base clock (f_W) divisor of CSIA0[Note]						
			f_W = 1 MHz	f_W = 2 MHz	f_W = 2.5 MHz	f_W = 5 MHz	f_W = 10 MHz	f_W = 20 MHz
0	0	$f_W/6$	166.67 kHz	333.3 kHz	416.67 kHz	833.33 kHz	1.67 MHz	Setting prohibited
0	1	$f_W/2^3$	125 kHz	250 kHz	312.5 kHz	625 kHz	1.25 MHz	Setting prohibited
1	0	$f_W/2^4$	62.5 kHz	125 kHz	156.25 kHz	312.5 kHz	625 kHz	1.25 MHz
1	1	$f_W/2^5$	31.25 kHz	62.5 kHz	78.125 kHz	156.25 kHz	312.5 kHz	625 kHz

Note Set the transfer clock so as to satisfy the following conditions.

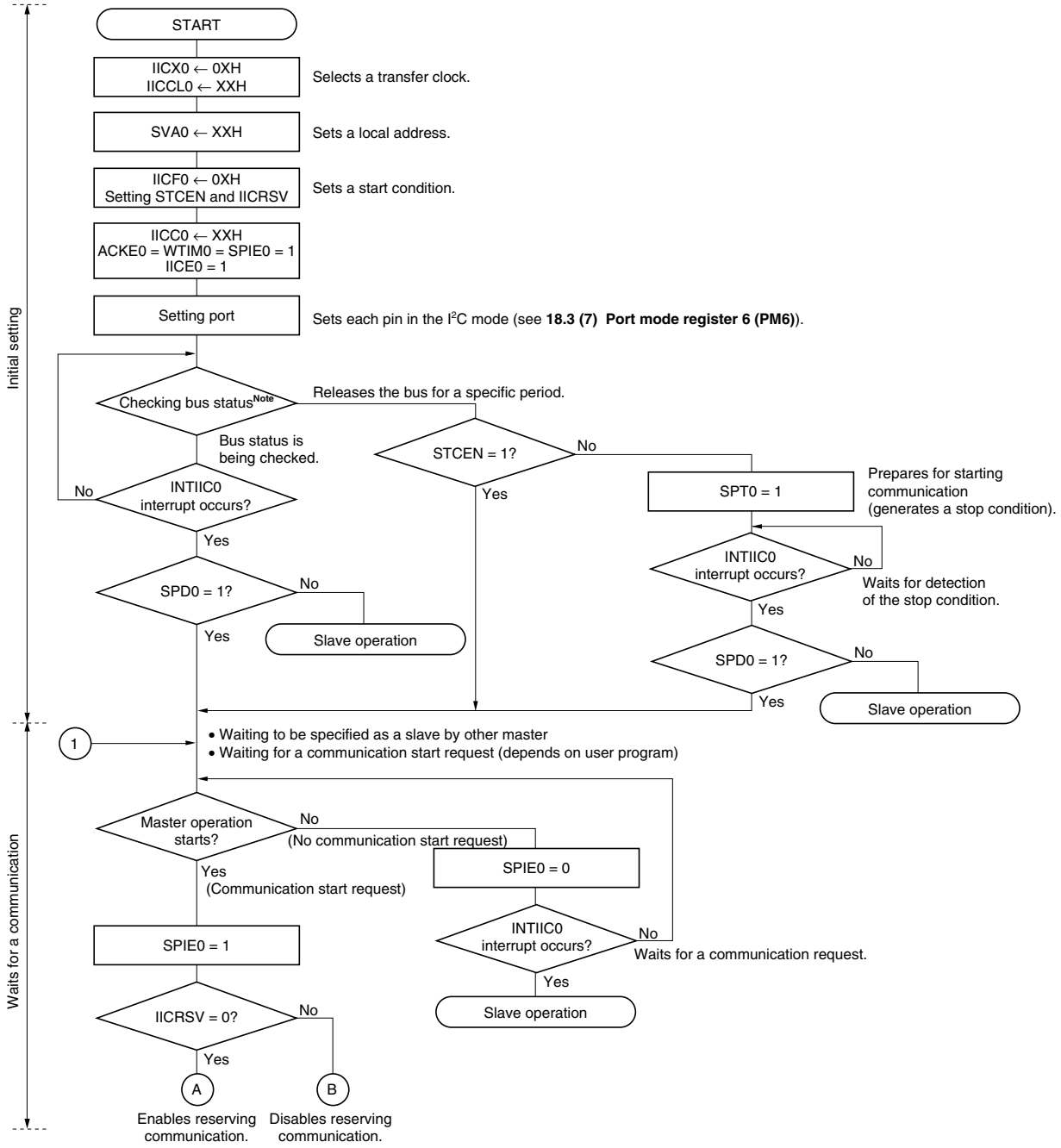
- When 4.0 V ≤ V_{DD} ≤ 5.5 V: transfer clock ≤ 1.67 MHz
- When 2.7 V ≤ V_{DD} < 4.0 V: transfer clock ≤ 833.33 kHz
- When 1.8 V ≤ V_{DD} < 2.7 V: transfer clock ≤ 555.56 kHz (Standard products and (A) grade products only)

Remark f_W: Base clock frequency selected by CKS00 bit of CSIS0 register (f_{PRS} or $f_{PRS}/2$)

f_{PRS}: Peripheral hardware clock frequency

(2) Master operation in multi-master system

Figure 18-24. Master Operation in Multi-Master System (1/3)



Note Confirm that the bus is released (CLD0 bit = 1, DAD0 bit = 1) for a specific period (for example, for a period of one frame). If the SDA0 pin is constantly at low level, decide whether to release the I^2C bus (SCL0 and SDA0 pins = high level) in conformance with the specifications of the product that is communicating.

Figure 26-1. Format of Option Byte (2/2)

Address: 0081H/1081H[Notes 1, 2]

7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	POCMODE

POCMODE	POC mode selection
0	1.59 V POC mode (default)
1	2.7 V/1.59 V POC mode

Notes 1. POCMODE can only be written by using a dedicated flash memory programmer. It cannot be set during self-programming or boot swap operation during self-programming. However, because the value of 1081H is copied to 0081H during the boot swap operation, it is recommended to set a value that is the same as that of 0081H to 1081H when the boot swap function is used.

2. To change the setting for the POC mode, set the value to 0081H again after batch erasure (chip erasure) of the flash memory. The setting cannot be changed after the memory of the specified block is erased.

Caution Be sure to clear bits 7 to 1 to "0".

Address: 0082H/1082H, 0083H/1083H[Note]

7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	0

Note Be sure to set 00H to 0082H and 0083H, as these addresses are reserved areas. Also set 00H to 1082H and 1083H because 0082H and 0083H are switched with 1082H and 1083H when the boot swap operation is used.

Address: 0084H/1084H[Notes1, 2]

7	6	5	4	3	2	1	0
0	0	0	0	0	0	OCDEN1	OCDEN0

OCDEN1	OCDEN0	On-chip debug operation control
0	0	Operation disabled
0	1	Setting prohibited
1	0	Operation enabled. Does not erase data of the flash memory in case authentication of the on-chip debug security ID fails.
1	1	Operation enabled. Erases data of the flash memory in case authentication of the on-chip debug security ID fails.

Notes 1. Be sure to set 00H (on-chip debug operation disabled) to 0084H for products not equipped with the on-chip debug function (μPD78F05xx and 78F05xxA). Also set 00H to 1084H because 0084H and 1084H are switched during the boot swap operation.

2. To use the on-chip debug function with a product equipped with the on-chip debug function (μPD78F05xxD and 78F05xxDA), set 02H or 03H to 0084H. Set a value that is the same as that of 0084H to 1084H because 0084H and 1084H are switched during the boot swap operation.

Remark For the on-chip debug security ID, see **CHAPTER 28 ON-CHIP DEBUG FUNCTION (μPD78F05xxD and 78F05xxDA ONLY)**.

CHAPTER 27 FLASH MEMORY

The 78K0/Kx2 microcontrollers incorporates the flash memory to which a program can be written, erased, and overwritten while mounted on the board.

27.1 Internal Memory Size Switching Register

Select the internal memory capacity using the internal memory size switching register (IMS).
IMS is set by an 8-bit memory manipulation instruction.
Reset signal generation sets IMS to CFH.

Caution Be sure to set each product to the values shown in Table 27-1 after a reset release.

Figure 27-1. Format of Internal Memory Size Switching Register (IMS)

Address: FFF0H After reset: CFH R/W

Symbol	7	6	5	4	3	2	1	0
IMS	RAM2	RAM1	RAM0	0	ROM3	ROM2	ROM1	ROM0

RAM2	RAM1	RAM0	Internal high-speed RAM capacity selection
0	0	0	768 bytes
0	1	0	512 bytes
1	1	0	1024 bytes
Other than above			Setting prohibited

ROM3	ROM2	ROM1	ROM0	Internal ROM capacity selection
0	0	1	0	8 KB
0	1	0	0	16 KB
0	1	1	0	24 KB
1	0	0	0	32 KB
1	1	0	0	48 KB
1	1	1	1	60 KB
Other than above				Setting prohibited

Caution To set the memory size, set IMS and then IXS. Set the memory size so that the internal ROM and internal expansion RAM areas do not overlap.

Caution The pins mounted depend on the product. Refer to Caution 2 at the beginning of this chapter.

Internal Oscillator Characteristics

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} = EV_{DD} ≤ 5.5 V, V_{SS} = EV_{SS} = AV_{SS} = 0 V)

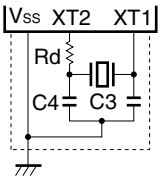
Resonator	Parameter	Conditions		MIN.	TYP.	MAX.	Unit
8 MHz internal oscillator	Internal high-speed oscillation clock frequency (f_{RH})[Note]	RSTS = 1	2.7 V ≤ V_{DD} ≤ 5.5 V	7.6	8.0	8.4	MHz
			1.8 V ≤ V_{DD} < 2.7 V	7.6	8.0	10.4	MHz
		RSTS = 0		2.48	5.6	9.86	MHz
240 kHz internal oscillator	Internal low-speed oscillation clock frequency (f_{RL})	2.7 V ≤ V_{DD} ≤ 5.5 V		216	240	264	kHz
		1.8 V ≤ V_{DD} < 2.7 V		192	240	264	kHz

Note Indicates only oscillator characteristics. Refer to **AC Characteristics** for instruction execution time.

Remark RSTS: Bit 7 of the internal oscillation mode register (RCM)

XT1 Oscillator Characteristics[Note 1]

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} = EV_{DD} ≤ 5.5 V, V_{SS} = EV_{SS} = AV_{SS} = 0 V)

Resonator	Recommended Circuit	Parameter	Conditions	MIN.	TYP.	MAX.	Unit
Crystal resonator		XT1 clock oscillation frequency (f_{XT})[Note 2]		32	32.768	35	kHz

Notes 1. The 78K0/KB2 is not provided with the XT1 oscillator.

2. Indicates only oscillator characteristics. Refer to **AC Characteristics** for instruction execution time.

Cautions 1. When using the XT1 oscillator, wire as follows in the area enclosed by the broken lines in the above figure to avoid an adverse effect from wiring capacitance.

- **Keep the wiring length as short as possible.**
- **Do not cross the wiring with the other signal lines.**
- **Do not route the wiring near a signal line through which a high fluctuating current flows.**
- **Always make the ground point of the oscillator capacitor the same potential as V_{SS}.**
- **Do not ground the capacitor to a ground pattern through which a high current flows.**
- **Do not fetch signals from the oscillator.**

2. The XT1 oscillator is designed as a low-amplitude circuit for reducing power consumption, and is more prone to malfunction due to noise than the X1 oscillator. Particular care is therefore required with the wiring method when the XT1 clock is used.

Caution The pins mounted depend on the product. Refer to Caution 2 at the beginning of this chapter.

DC Characteristics (2/4)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} = EV_{DD} ≤ 5.5 V, AV_{REF} ≤ V_{DD}, V_{SS} = EV_{SS} = AV_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Input voltage, high (products whose flash memory is at least 48 KB)[Note 1]	V_{IH1}	P02, P12, P13, P15, P40 to P47, P50 to P57, P64 to P67, P121 to P124, P144, P145, EXCLK, EXCLKS		0.7V_{DD}		V_{DD}	V
	V_{IH2}	P00, P01, P03 to P06, P10, P11, P14, P16, P17, P30 to P33, P70 to P77, P120, P140 to P143, $\overline{RESET}$		0.8V_{DD}		V_{DD}	V
	V_{IH3}	P20 to P27	AV_{REF} = V_{DD}	0.7AV_{REF}		AV_{REF}	V
	V_{IH4}	P60 to P63		0.7V_{DD}		6.0	V
Input voltage, high (products whose flash memory is less than 32 KB)[Note 2]	V_{IH1}	P02 to P06, P12, P13, P15, P40 to P43, P50 to P53, P121 to P124, EXCLK, EXCLKS		0.7V_{DD}		V_{DD}	V
	V_{IH2}	P00, P01, P10, P11, P14, P16, P17, P30 to P33, P70 to P77, P120, P140, P141, $\overline{RESET}$		0.8V_{DD}		V_{DD}	V
	V_{IH3}	P20 to P27	AV_{REF} = V_{DD}	0.7AV_{REF}		AV_{REF}	V
	V_{IH4}	P60 to P63		0.7V_{DD}		6.0	V
Input voltage, low (products whose flash memory is at least 48 KB)[Note 1]	V_{IL1}	P02, P12, P13, P15, P40 to P47, P50 to P57, P60 to P67, P121 to P124, P144, P145, EXCLK, EXCLKS		0		0.3V_{DD}	V
	V_{IL2}	P00, P01, P03 to P06, P10, P11, P14, P16, P17, P30 to P33, P70 to P77, P120, P140 to P143, $\overline{RESET}$		0		0.2V_{DD}	V
	V_{IL3}	P20 to P27	AV_{REF} = V_{DD}	0		0.3AV_{REF}	V
Input voltage, low (products whose flash memory is less than 32 KB)[Note 2]	V_{IL1}	P02 to P06, P12, P13, P15, P40 to P43, P50 to P53, P60 to P63, P121 to P124, EXCLK, EXCLKS		0		0.3V_{DD}	V
	V_{IL2}	P00, P01, P10, P11, P14, P16, P17, P30 to P33, P70 to P77, P120, P140, P141, $\overline{RESET}$		0		0.2V_{DD}	V
	V_{IL3}	P20 to P27	AV_{REF} = V_{DD}	0		0.3AV_{REF}	V
Output voltage, high	V_{OH1}	P00 to P06, P10 to P17, P30 to P33, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P120, P130, P140 to P145	4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OH1} = –3.0 mA	V_{DD} – 0.7			V
			2.7 V ≤ V_{DD} < 4.0 V, I_{OH1} = –2.5 mA	V_{DD} – 0.5			V
			1.8 V ≤ V_{DD} < 2.7 V, I_{OH1} = –1.0 mA	V_{DD} – 0.5			V
	V_{OH2}	P20 to P27	AV_{REF} = V_{DD}, I_{OH2} = –100 μA	V_{DD} – 0.5			V
		P121 to P124	I_{OH2} = –100 μA	V_{DD} – 0.5			V

Notes 1. Supported products: 78K0/KD2 and 78K0/KE2 whose flash memory is at least 48 KB, and 78K0/KF2

2. Supported products: 78K0/KD2 and 78K0/KE2 whose flash memory is less than 32 KB, 78K0/KB2, and 78K0/KC2

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

Caution The pins mounted depend on the product. Refer to Caution at the beginning of this chapter.

Absolute Maximum Ratings (T_A = 25°C) (1/2)

Parameter	Symbol	Conditions	Ratings	Unit
Supply voltage	V_{DD}		−0.5 to +6.5	V
	EV_{DD}		−0.5 to +6.5	V
	V_{SS}		−0.5 to +0.3	V
	EV_{SS}		−0.5 to +0.3	V
	AV_{REF}		−0.5 to V_{DD} + 0.3[Note]	V
	AV_{SS}		−0.5 to +0.3	V
REGC pin input voltage	V_{IREGC}		−0.5 to +3.6 and −0.5 to V_{DD}	V
Input voltage	V_{I1}	P00 to P06, P10 to P17, P20 to P27, P30 to P33, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P120 to P124, P140 to P145, X1, X2, XT1, XT2, $\overline{\text{RESET}}$, FLMD0	−0.3 to V_{DD} + 0.3[Note]	V
	V_{I2}	P60 to P63 (N-ch open drain)	−0.3 to +6.5	V
Output voltage	V_O		−0.3 to V_{DD} + 0.3[Note]	V
Analog input voltage	V_{AN}	ANI0 to ANI7	−0.3 to AV_{REF} + 0.3[Note] and −0.3 to V_{DD} + 0.3[Note]	V

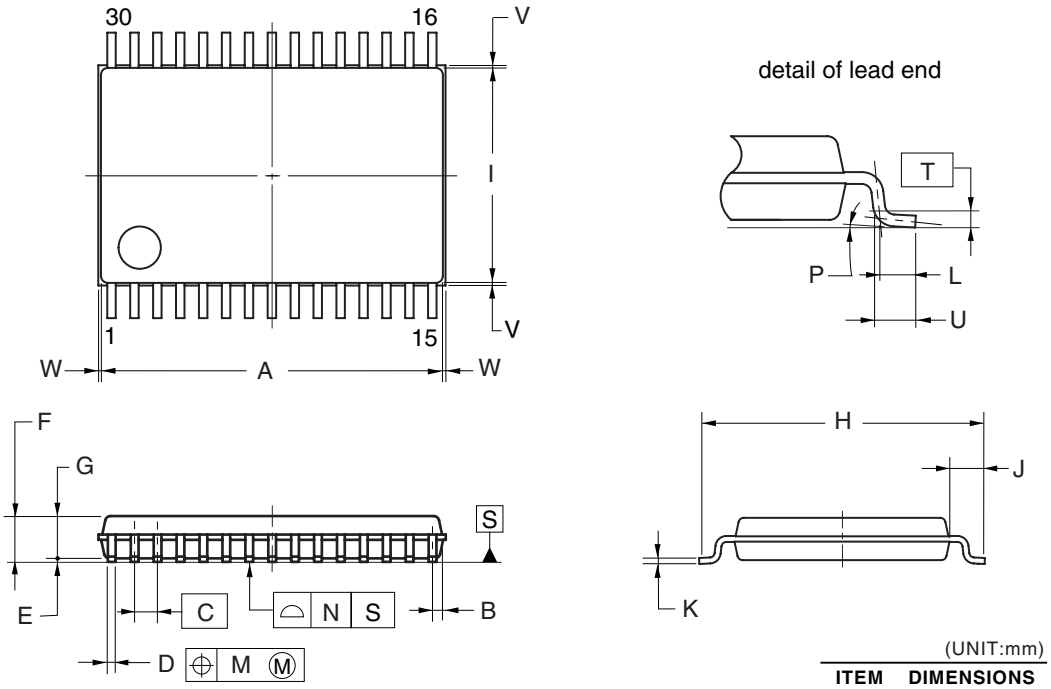
Note Must be 6.5 V or lower.

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

- μPD78F0500MC(A)-CAB-AX, 78F0501MC(A)-CAB-AX, 78F0502MC(A)-CAB-AX, 78F0503MC(A)-CAB-AX
- μPD78F0500MC(A2)-CAB-AX, 78F0501MC(A2)-CAB-AX, 78F0502MC(A2)-CAB-AX, 78F0503MC(A2)-CAB-AX
- μPD78F0500AMC-CAB-AX, 78F0501AMC-CAB-AX, 78F0502AMC-CAB-AX, 78F0503AMC-CAB-AX, 78F0503DAMC-CAB-AX
- μPD78F0500AMCA-CAB-G, 78F0501AMCA-CAB-G, 78F0502AMCA-CAB-G, 78F0503AMCA-CAB-G
- μPD78F0500AMCA2-CAB-G, 78F0501AMCA2-CAB-G, 78F0502AMCA2-CAB-G, 78F0503AMCA2-CAB-G

30-PIN PLASTIC SSOP (7.62mm (300))



(UNIT:mm)

ITEM	DIMENSIONS
A	9.70±0.10
B	0.30
C	0.65 (T.P.)
D	$0.22^{+0.10}_{-0.05}$
E	0.10±0.05
F	1.30±0.10
G	1.20
H	8.10±0.20
I	6.10±0.10
J	1.00±0.20
K	$0.15^{+0.05}_{-0.01}$
L	0.50
M	0.13
N	0.10
P	$3^{\circ}{}^{+5^{\circ}}_{-3^{\circ}}$
T	0.25(T.P.)
U	0.60±0.15
V	0.25 MAX.
W	0.15 MAX.

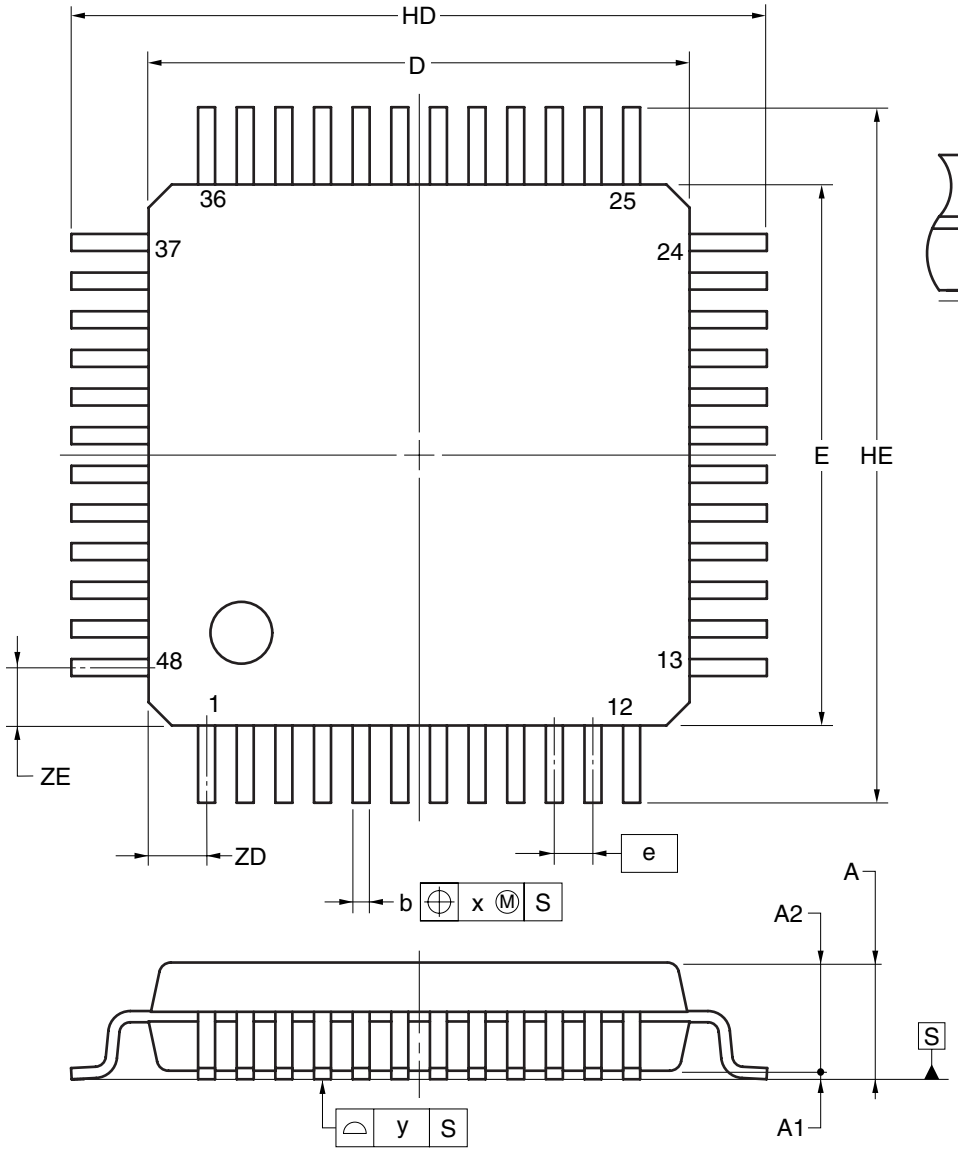
P30MC-65-CAB

NOTE

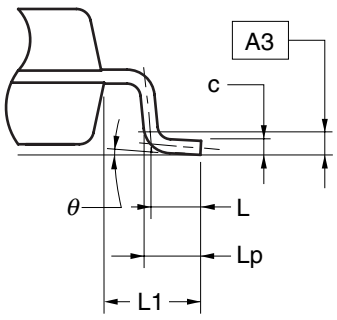
Each lead centerline is located within 0.13 mm of its true position (T.P.) at maximum material condition.

- μPD78F0511GA(A)-GAM-AX, 78F0512GA(A)-GAM-AX, 78F0513GA(A)-GAM-AX, 78F0514GA(A)-GAM-AX, 78F0515GA(A)-GAM-AX
- μPD78F0511GA(A2)-GAM-AX, 78F0512GA(A2)-GAM-AX, 78F0513GA(A2)-GAM-AX, 78F0514GA(A2)-GAM-AX, 78F0515GA(A2)-GAM-AX
- μPD78F0511AGA-GAM-AX, 78F0512AGA-GAM-AX, 78F0513AGA-GAM-AX, 78F0514AGA-GAM-AX, 78F0515AGA-GAM-AX, 78F0515DAGA-GAM-AX
- μPD78F0511AGAA-GAM-G, 78F0512AGAA-GAM-G, 78F0513AGAA-GAM-G, 78F0514AGAA-GAM-G, 78F0515AGAA-GAM-G
- μPD78F0511AGAA2-GAM-G, 78F0512AGAA2-GAM-G, 78F0513AGAA2-GAM-G, 78F0514AGAA2-GAM-G, 78F0515AGAA2-GAM-G

48-PIN PLASTIC LQFP (FINE PITCH) (7x7)



detail of lead end



(UNIT:mm)

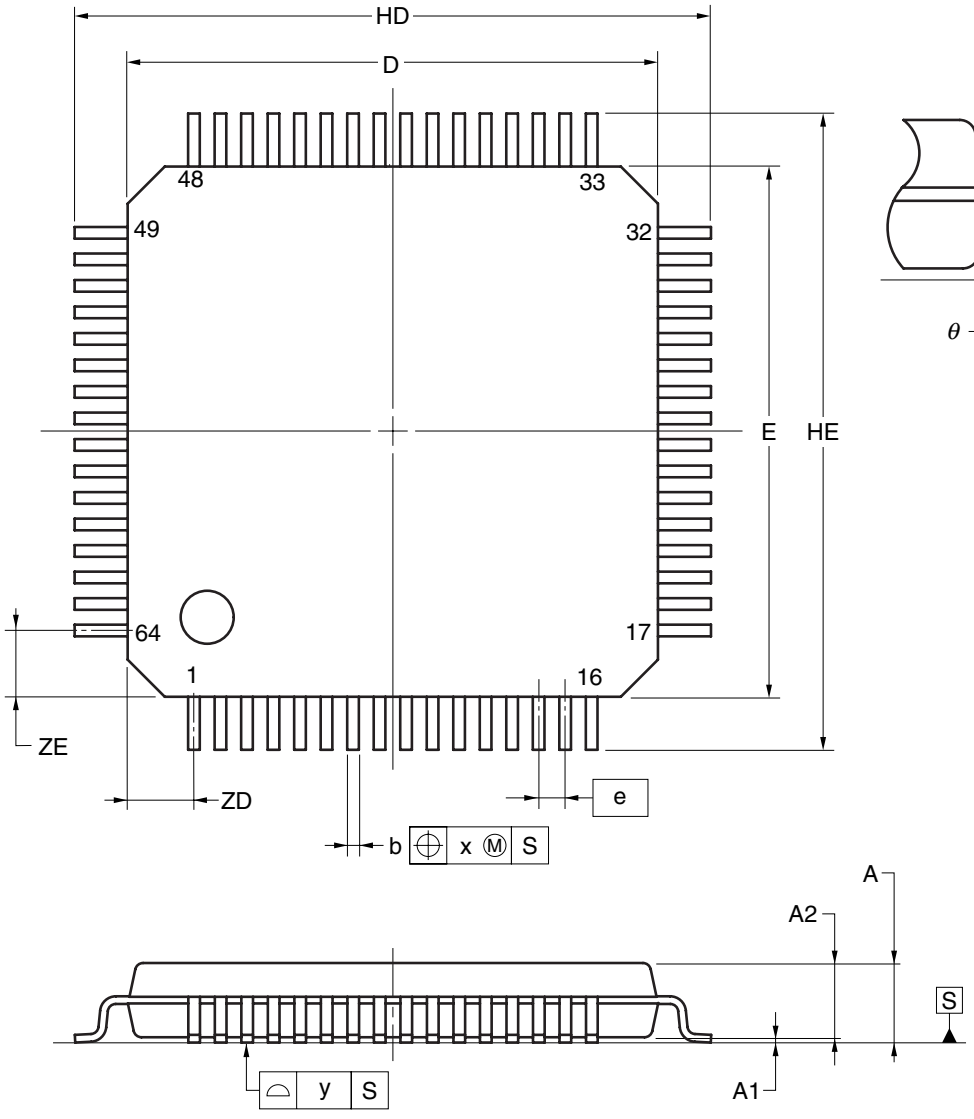
ITEM	DIMENSIONS
D	7.00±0.20
E	7.00±0.20
HD	9.00±0.20
HE	9.00±0.20
A	1.60 MAX.
A1	0.10±0.05
A2	1.40±0.05
A3	0.25
b	$0.20^{+0.07}_{-0.03}$
c	$0.125^{+0.075}_{-0.025}$
L	0.50
Lp	0.60±0.15
L1	1.00±0.20
θ	$3^{\circ}{}^{+5^{\circ}}_{-3^{\circ}}$
e	0.50
x	0.08
y	0.08
ZD	0.75
ZE	0.75

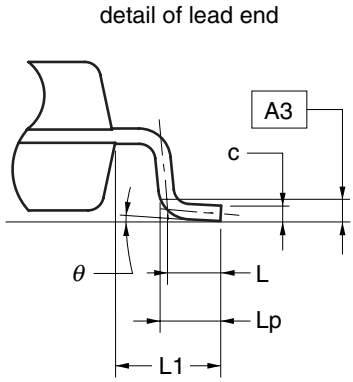
P48GA-50-GAM

NOTE
Each lead centerline is located within 0.08 mm of its true position at maximum material condition.

- μPD78F0531GB(A)-GAH-AX, 78F0532GB(A)-GAH-AX, 78F0533GB(A)-GAH-AX, 78F0534GB(A)-GAH-AX, 78F0535GB(A)-GAH-AX, 78F0536GB(A)-GAH-AX, 78F0537GB(A)-GAH-AX
- μPD78F0531GB(A2)-GAH-AX, 78F0532GB(A2)-GAH-AX, 78F0533GB(A2)-GAH-AX, 78F0534GB(A2)-GAH-AX, 78F0535GB(A2)-GAH-AX, 78F0536GB(A2)-GAH-AX, 78F0537GB(A2)-GAH-AX
- μPD78F0531AGB-GAH-AX, 78F0532AGB-GAH-AX, 78F0533AGB-GAH-AX, 78F0534AGB-GAH-AX, 78F0535AGB-GAH-AX, 78F0536AGB-GAH-AX, 78F0537AGB-GAH-AX, 78F0537DAGB-GAH-AX
- μPD78F0531AGBA-GAH-G, 78F0532AGBA-GAH-G, 78F0533AGBA-GAH-G, 78F0534AGBA-GAH-G, 78F0535AGBA-GAH-G, 78F0536AGBA-GAH-G, 78F0537AGBA-GAH-G
- μPD78F0531AGBA2-GAH-G, 78F0532AGBA2-GAH-G, 78F0533AGBA2-GAH-G, 78F0534AGBA2-GAH-G, 78F0535AGBA2-GAH-G, 78F0536AGBA2-GAH-G, 78F0537AGBA2-GAH-G

64-PIN PLASTIC LQFP(FINE PITCH)(10x10)





(UNIT:mm)

ITEM	DIMENSIONS
D	10.00±0.20
E	10.00±0.20
HD	12.00±0.20
HE	12.00±0.20
A	1.60 MAX.
A1	0.10±0.05
A2	1.40±0.05
A3	0.25
b	$0.20^{+0.07}_{-0.03}$
c	$0.125^{+0.075}_{-0.025}$
L	0.50
Lp	0.60±0.15
L1	1.00±0.20
θ	$3^{\circ}{}^{+5^{\circ}}_{-3^{\circ}}$
e	0.50
x	0.08
y	0.08
ZD	1.25
ZE	1.25

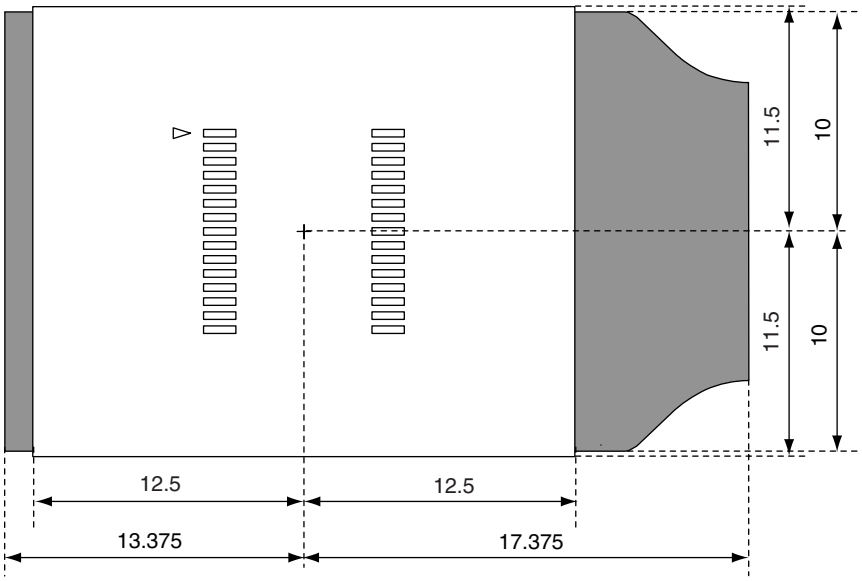
P64GB-50-GAH

NOTE
Each lead centerline is located within 0.08 mm of its true position at maximum material condition.

APPENDIX B NOTES ON TARGET SYSTEM DESIGN

This chapter shows areas on the target system where component mounting is prohibited and areas where there are component mounting height restrictions when the QB-78K0KX2 is used.

Figure B-1. For 30-Pin MC Package



□ : Exchange adapter area: Components up to 17.45 mm in height can be mounted[Note]

■ : Emulation probe tip area: Components up to 24.45 mm in height can be mounted[Note]

Note Height can be adjusted by using space adapters (each adds 2.4 mm)